NXP

Customer Information Notification   2020070411

Issue Date: 12-Aug-2020
Effective Date: 13-Aug-2020

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QUALITY

Management Summary

In order to improve material management and device traceability, NXP is modifying the topside marking of the FXTH87xxxxx product family to include a 2D Data Matrix Code.

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[X] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

Package Marking Change to Include 2D Data Matrix Code on the FXTH87xxxxx Product Family

Description

NXP is pleased to announce a product marking change for the FXTH87xxxxx product family, which will improve material management and device traceability. NXP is modifying the topside marking to include a 2D Data Matrix Code (DMC). The initial rollout will display an outline for the 2D DMC, with the 2D DMC implemented in its place at a later date. The FSL logo will be shifted closer to the Pin 1 mark to accommodate for the additional 2D Data Matrix Code. The product part number will be replaced with a product family code while the tracecode marking will be unchanged.

Reason

NXP proposes the marking change in order to add a 2D Data Matrix Code to the topside of the product for improved product traceability. The new 2D Data Matrix Code, once fully implemented, will link with upcoming internal database improvements to allow quicker individual part tracing through the manufacturing line for any quality concern.

Identification of Affected Products

Top side marking

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Only change to the topside marking, as noted.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

A clean date for assembly conversion can be provided upon request.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Affected Part Numbers

FXTH871511DT1

FXTH8709116T1

FXTH87EH11DT1

FXTH87EH026T1

FXTH87EH116T1

FXTH87EH118T1

FXTH87EH02DT1